

Amendments to the Specification:

Please replace the paragraph beginning on page 7, line 7, with the following amended paragraph:

FIG. 1 shows a module 1. The module 1 is designed to be plate-shaped and has an overall height that is ~~as low possible as low as possible~~: in this case, this is around 220 μm . The overall height can lie within a range of between 190 μm and 400 μm . The module 1 comprises a conductor frame configuration 2 and a chip 3. The chip 3 contains a circuit, not shown, with the aid of which contactless communication can be carried out with a communication station that is suitable for this. The chip 3 has chip connection contacts 4, 5 and 6, 7. We shall go into further detail about the purpose of the connection contacts 4 to 7 below.